



Title of Change:	NCV7518MWTXG Dual Source Introduction to Pocatello Wafer Fab
Proposed first ship date:	1 September 2017
Contact information:	Contact your local ON Semiconductor Sales Office or your Customer Quality interface
Samples:	Contact your local ON Semiconductor Sales Office or your Customer Quality interface
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 12 months prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>
Change Part Identification:	<p>The OPN and the part marking will be updated:</p> <p>New Dual Source OPN: NCV7518MWATXG New Part Marking: NCV7518A</p>
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Pocatello, Idaho <input type="checkbox"/> External Foundry/Subcon site(s)
Description and Purpose	
Wafer fab dual site introduction for device NCV7518MWTXG. Current site: ON Semiconductor Oudenaarde, Belgium Additional Site: ON Semiconductor Pocatello, Idaho, USA Purpose of change is to introduce wafer fab dual sourcing.	



Qualification Plan:

Test	Specification	Condition	Interval	Results
PC	JESD22 A113 J-STD-020	MSL 3 @ 260 °C		
HAST	JESD22 A110	130°C/85% RH, 18.8psi, bias	96 hrs	
UHAST	JESD22 A118	130°C/85% RH, 18.8psi	96 hrs	
TC	JESD22 A104	-55°C to+150°C	500 cyc	
HTSL	JESD22 A103	Ta=150°C	1000 hrs	
HTOL	JESD22 A108	Tj=150°C, 100 % max rated Vcc	1500 hrs	
ELFR	AEC-Q100-008	Ta= 125°C	48 hrs	
WBS	AEC-Q100-001	Cpk >1.67	30 bonds	
WBP	Mil-Std-883 Method 2011	Cpk >1.67	30 bonds	
WBP	Mil-Std-883 Method 2011	Cpk >1.67	30 bonds	
HBM	AEC-Q100-002	Electrostatic Discharge, Human Body Model		
LU	AEC-Q100-004	Latch-up		
ED	AEC-Q100-009	Electrical Distribution Cpk >1.67	30 units	

Estimated date for qualification completion: Aug'2016

List of affected Standard Parts:

Current Part Number (Belgium Fab)	New Dual Source Part Number (Qualification Vehicle)
NCV7518MWTXG	NCV7518MWATXG